100V N-CHANNEL ENHANCEMENT MODE POWER MOSFET

Features

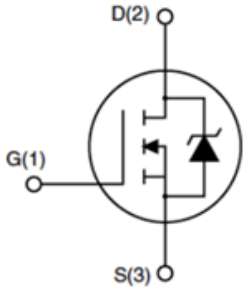
- 100V, 14.6A
- $R_{DS(ON)}$ =100mΩ (max.) @ V_{GS} = 10V, I_D = 5A
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- RoHS Compliant & Halogen-Free

Application

- Synchronous buck converter applications.

Package

TO-252



Absolute Maximum Ratings T_C=25℃ unless otherwise specified

Symbol	Parameter		Max.	Units
V_{DS}	Drain-Source Voltage		100	V
V_{GS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current, VGS @ 10Vno[note1,6]	T_C = 25℃	14.6	A
		T_C = 100℃	10	A
I_{DM}	Pulsed Drain Current [note2]		25	A
P_D	Power Dissipation [note4]	T_C = 25℃	30	W
E_{AS}	Single Pulsed Avalanche Energy [note3]		0.8	mJ
$R_{\theta JA}$	Thermal Resistance, Junction to Case [note1]		3	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	℃

Electrical Characteristics T_C=25℃ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V,I_D = 250μA	100	-	-	V
I_{DSS}	Drain-Source Leakage Current	V_{DS} = 80V, V_{GS} = 0V	-	-	10	μA
		V_{DS} = 80V, T_C = 55℃	-	-	100	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.2	-	2.9	V
$R_{DS(on)}$	Static Drain-Source On-Resistance note2	V_{GS} = 10V, I_D =5A	-	-	100	mΩ
		V_{GS} = 4.5V, I_D =3A	-	-	110	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 5V, I_D =5A	-	14	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 15V, V_{GS} = 0V, f = 1.0MHz	-	450	-	pF
C_{oss}	Output Capacitance		-	55	-	pF
C_{rss}	Reverse Transfer Capacitance		-	16	-	pF
Q_g	Total Gate Charge	V_{Ds} =50V, I_D =5A, V_{GS} = 10V	-	11.9	-	nC
Q_{gs}	Gate-Source Charge		-	2.8	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	1.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 50V, I_D =5A, R_G = 3.3Ω, V_{GS} = 10V	-	3.8	-	ns
t_r	Turn-On Rise Time		-	25.8	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	16	-	ns
t_f	Turn-Off Fall Time		-	8.8	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current note1,5		-	-	14.6	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current note2,5		-	-	25	A
V_{SD} note2	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S = 1A	-	-	1.2	V

Note :

1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=50A

4.The power dissipation is limited by 150℃ junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

6.Package limitation current is 85A.

Typical Performance Characteristics

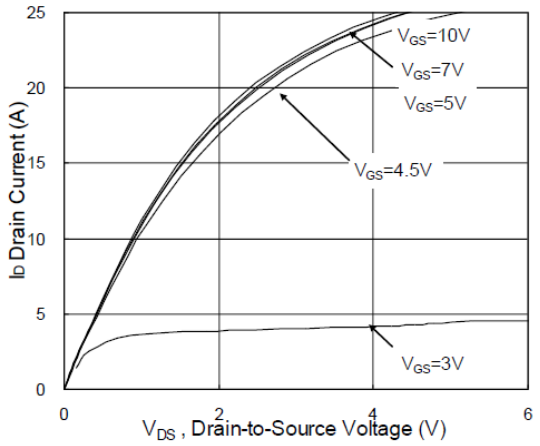


Figure 1. Output Characteristics

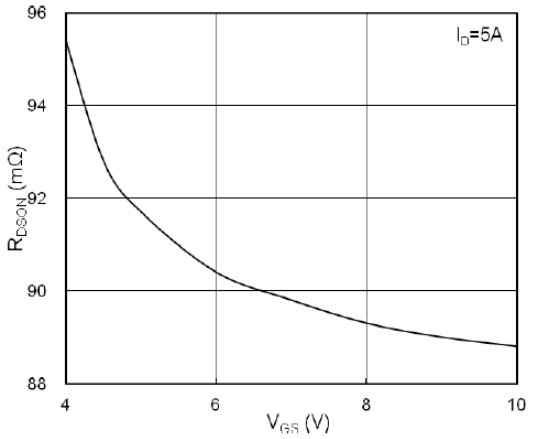


Figure 2. On Resistance vs. Gate-Source Voltage

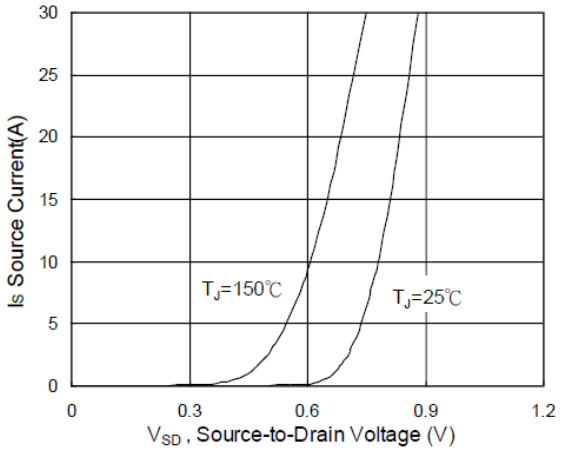


Figure 3. Body Diode Forward Voltage vs. Source Current and Temperature

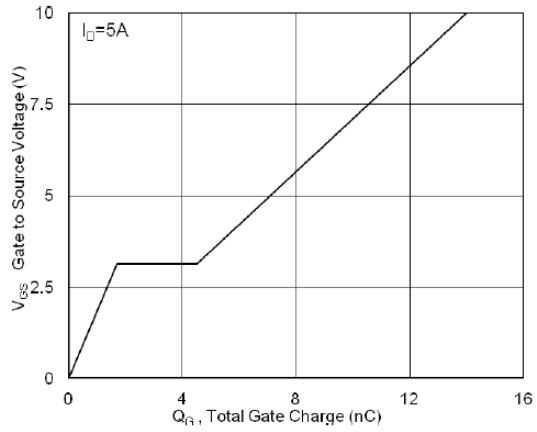


Figure 4. Gate Charge Characteristics

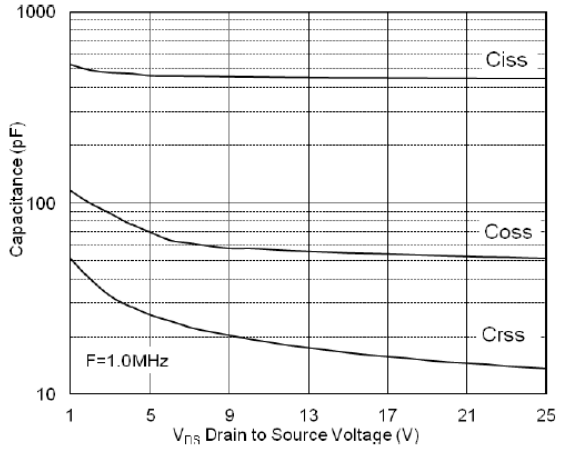


Figure 5. Capacitance Characteristics

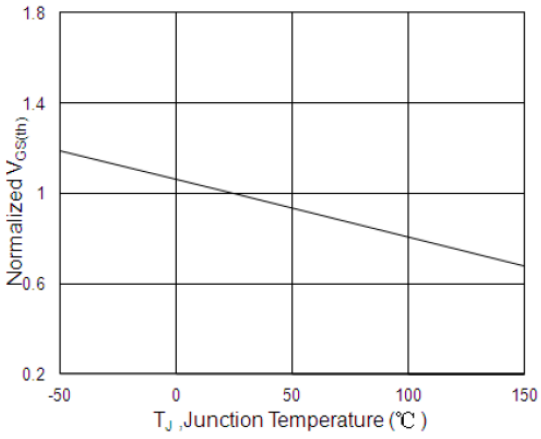


Figure 6. Normalized Threshold Voltage vs. Junction Temperature

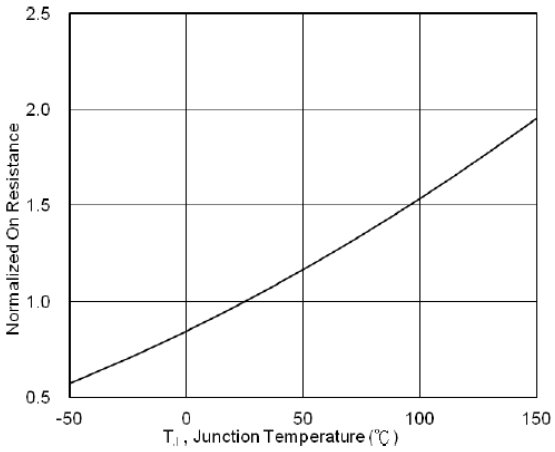


Figure 7. N Normalized On Resistance vs. Junction Temperature

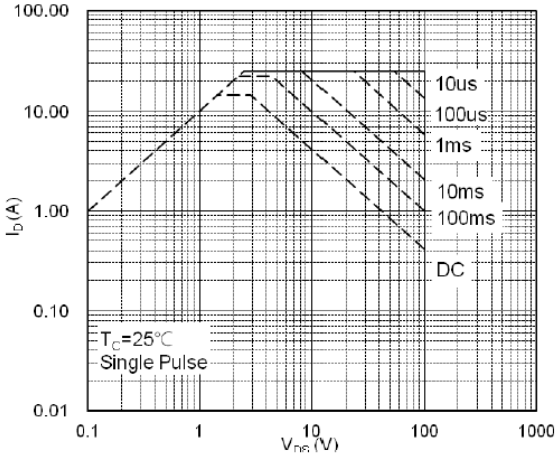


Figure 8. Maximum Safe Operating Area

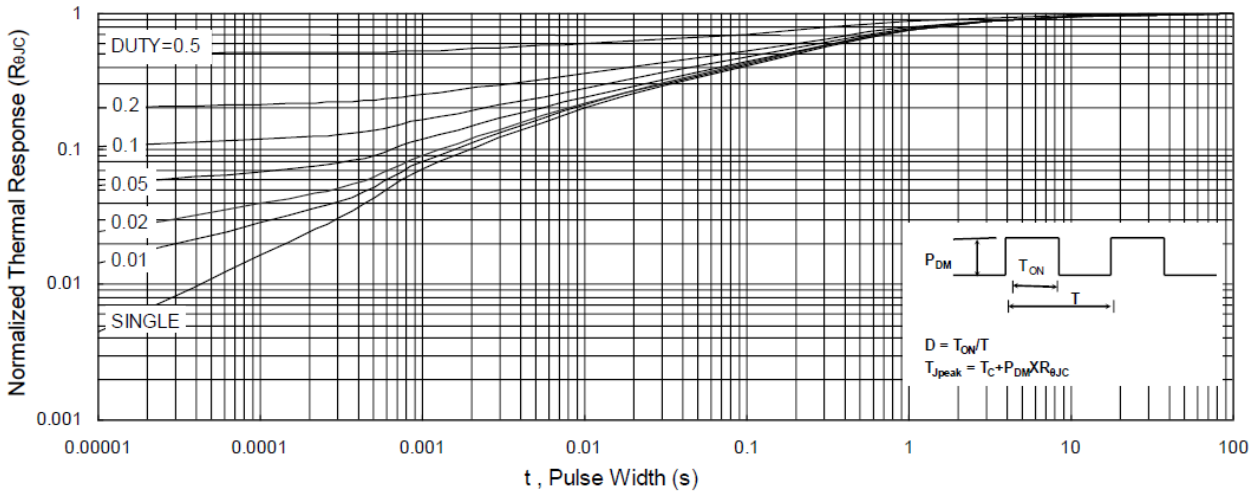


Figure 9. Effective Transient Thermal Impedance

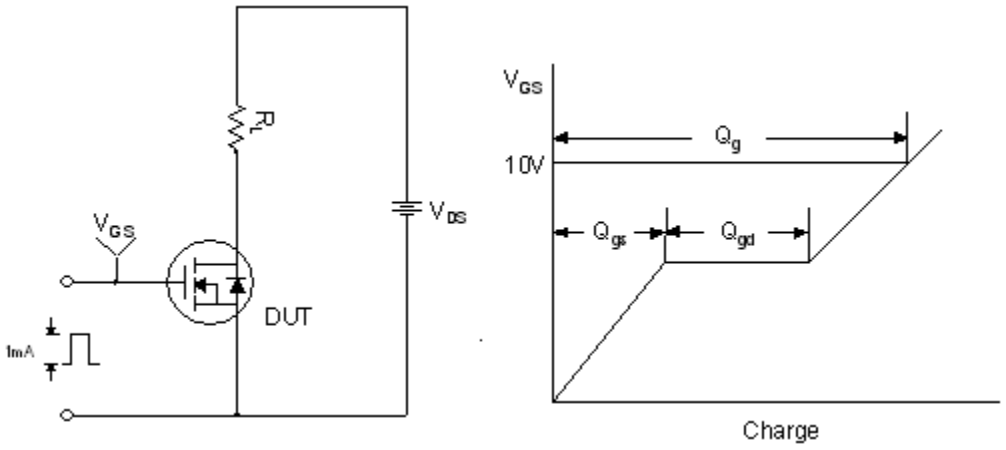


Figure 10. Gate Charge Test Circuit & Waveform

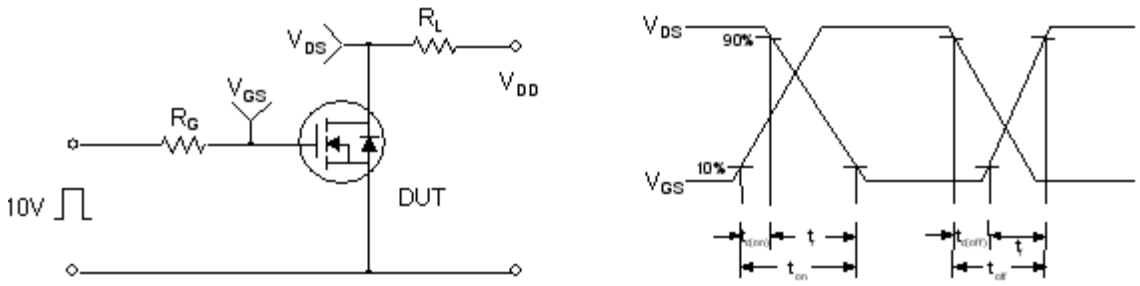


Figure 11. Resistive Switching Test Circuit & Waveforms

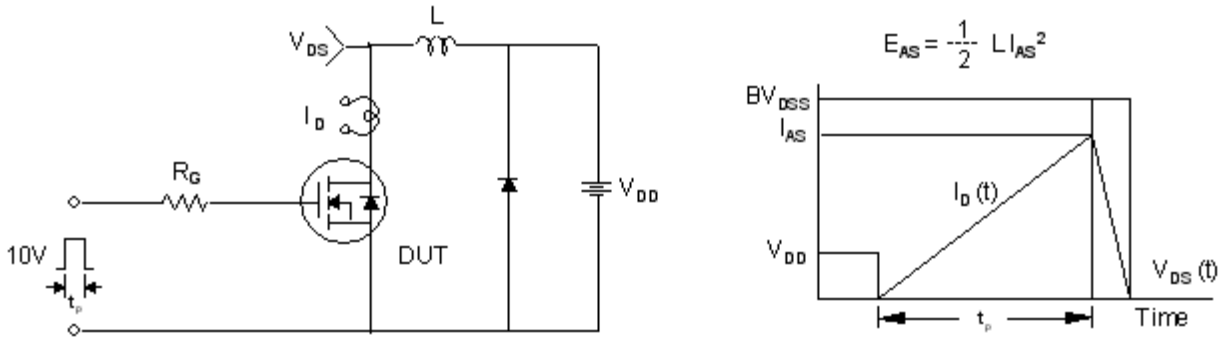


Figure 12. Unclamped Inductive Switching Test Circuit & Waveforms

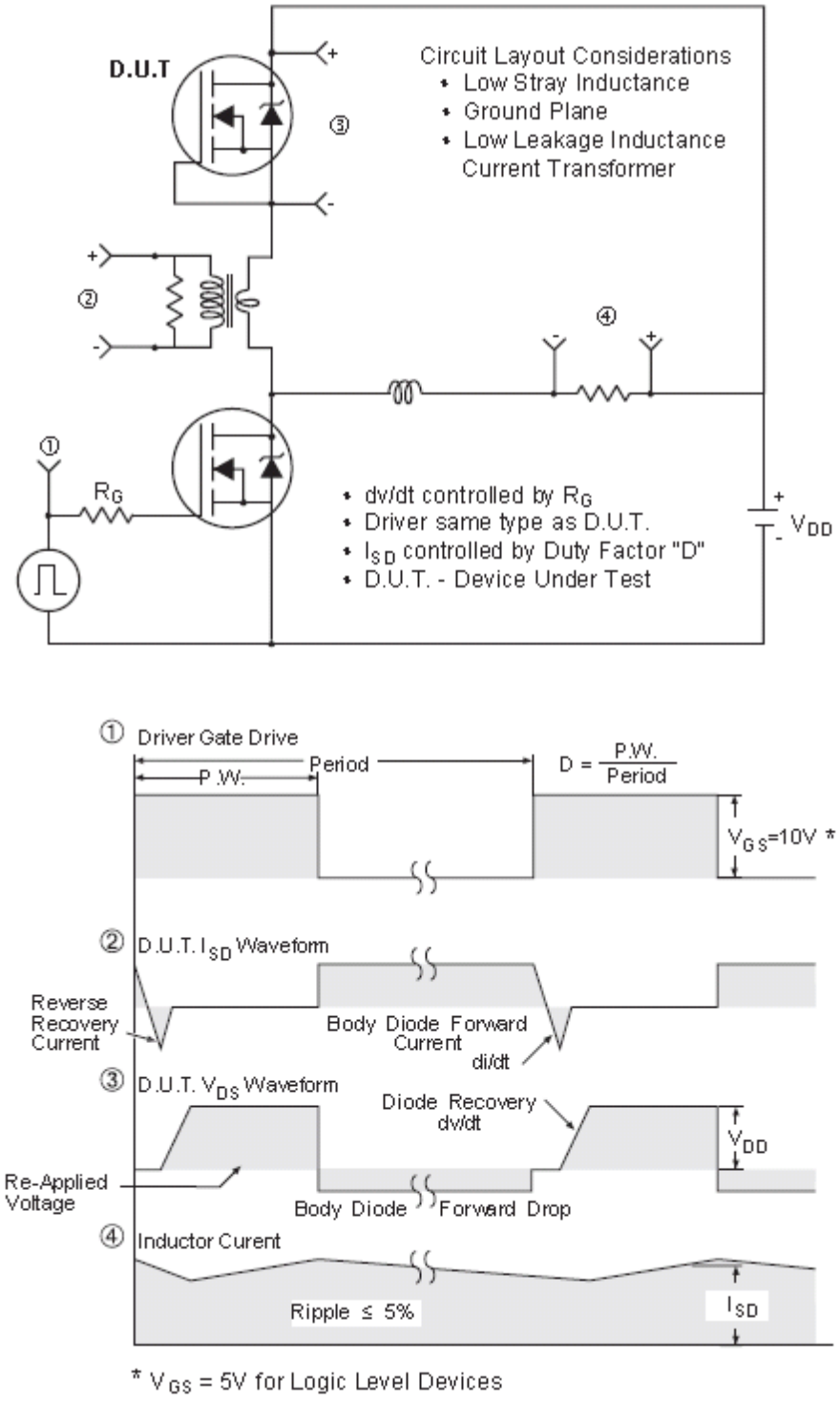


Figure 13. Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)